

CLAIMS

1. A composite magnetic body comprising soft magnetic powder dispersed in an organic binding agent, characterized in that heat conductive powder is further dispersed into said organic binding agent, thereby the composite magnetic body having a high thermal conductivity.

2. The composite magnetic body of claim 1, which is characterized in that said heat conductive powder is at least one kind of powder selected from the group of alumina (Al_2O_3) powder, aluminum nitride (AlN) powder, cubic boron nitride (BN) powder, insulating silicon carbide (SiC) powder and a heat conductive reinforcement (capton) powder.

3. The composite magnetic body of claim 1 or 2, which is characterized in that said organic binding agent is thermoplastic resin having a glass transition temperature of not less than 120°C.

4. The composite magnetic body as recited in claim 3, which is characterized in that said organic binding agent is at least one kind of thermoplastic polyimide and liquid crystal polymer.

5. An electromagnetic interference suppressing body characterized in that sheets of the composite magnetic body as recited in any of claims 1 to 4 are stacked on both

sides of an electrically conductive support.

6. A heat dissipation sheet comprising the composite magnetic body as recited in any of claims 1 to 4.

7. A heat sink comprising the composite magnetic body as recited in any of claims 1 to 4.

8. A composite magnetic body comprising soft magnetic powder dispersed in an organic binding agent, which is characterized in that said organic binding agent is thermoplastic resin having a glass transition temperature of not less than 120°C, thereby the composite magnetic body having heat resistivity.

9. The composite magnetic body of claim 8, which is characterized in that said organic binding agent is at least one kind of thermoplastic polyimide and liquid crystal polymer.

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